Super Low Loss and High Thermal Reliability Laminate and Prepreg





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# ThunderClad 3

Core: TU-933

Prepreg: TU-933P

ThunderClad 3 is an advanced material designed for high speed computing, telecommunications, radio frequency super low loss filed applications. ThunderClad 3's electrical performance is competitive with PTFE-based, hydrocarbon-based very low loss materials, but capable for high layer count circuit board design with excellent thermal reliability.

ThunderClad 3 laminates also exhibit excellent moisture resistance, improved CTE, superior chemical resistance, thermal stability, CAF resistance, and also compatible with modified FR-4 processes.

# **Applications**

- Radio frequency
- Backplane, High performance computing
- Line cards, Storage
- Servers, Telecom, Base station
- Office Routers

#### Performance and Processing Advantages

- Excellent electrical and thermal properties
- Dielectric constant is 3.4 @ 10Gz
- Dissipation factor is 0.0025 @ 10Ghz
- Stable and flat Dk/Df performance over frequency and temperature variance.
- Compatible with modified FR-4 processes
- Excellent moisture resistance and Lead Free reflow process compatible
- Improved z-axis thermal expansion
- Superior dimensional stability, thickness uniformity and flatness
- Anti-CAF capability
- Excellent through-hole and soldering reliability

# **Industry Approvals**

- IPC-4101E Specification Number: /102
- IPC-4101E/102 Validation Services QPL Certified
- UL File Number: E189572
- ANSI Grade: No-ANSI
- Flammability Rating: 94V-0
- Maximum Operating Temperature: 140°C

## Standard Availability

- Thickness: 0.002" [0.05mm] to 0.062" [1.58mm], available in sheet or panel form
- Copper Foil Cladding: 1/3 to 5 oz for built-up & double sides
- Prepregs: Available in roll or panel form
- Glass Styles: 1035, 1078, 2113, 2116 and other prepreg grades are available upon request.





**LISTED** 

# Super Low Loss and High Thermal Reliability Validation Services Laminate and Prepreg



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ROBS Compliant Lead Free Process Compatible





Typical Properties		
	Typical Values	Conditioning
Thermal		
Tg (DMA)	220 °C	
Tg (TMA)	170 ℃	E-2/105
Td (TGA)	390 ℃	
CTE z-axis α1	35 ppm/°C	
CTE z-axis α2	250 ppm/°C	E-2/105
CTE z-axis	2.7 %	
Thermal Stress,		
Solder Float, 288°C	> 120 sec	Α
T-260	> 60 min	
T-288	> 60 min	E-2/105
T-300	> 60 min	
Flammability	94V-0	E-24/125
Electrical		
Permittivity (RC50%)		
10 GHz (SPC method)	3.4	E-2/105
Loss Tangent (RC50%)		
10 GHz (SPC method)	0.0025	E-2/105
Volume Resistivity	$> 10^{10}  \mathrm{M}\Omega \! \cdot \! \mathrm{cm}$	C-96/35/90
Surface Resistivity	$> 10^8 \ M\Omega$	C-96/35/90
Electric Strength	> 40 KV/mm	Α
Dielectric Breakdown Voltage	> 50 KV	Α
Mechanical		
Young's Modulus		
Warp Direction	24 GPa	A
Fill Direction	22 GPa	A
Flexural Strength		
Lengthwise	> 60,000 psi	А
Crosswise	> 50,000 psi	7
Peel Strength,		
1.0 oz. Cu foil	4~6 lb/in	A
Water Absorption	0.06 %	E-1/105 + D-24/23

## NOTE:

- 1. Property values are for information purposes only and not intended for specification.
- 2. Any sales of these products will be governed by the terms and conditions of the agreement under which they are sold.
- 3. This product is based on a patent pending technology.

